

What is claimed is:

1. A multi-layer board comprising:
a ceramic layer;
a first resin layer over said ceramic layer; and
5 a first impedance element formed on said ceramic layer.
2. The multi-layer board of claim 1, wherein said first resin layer is provided with an electronic component mounted thereon.
- 10 3. The multi-layer board of claim 1, further comprising a second resin layer over said ceramic layer, said second resin layer being disposed at an opposite side of said first resin layer about said ceramic layer.
- 15 4. The multi-layer board of claim 3, further comprising a strip line formed on said second resin layer.
5. The multi-layer board of claim 3, further comprising a third resin layer over said first resin layer.
- 20 6. The multi-layer board of claim 5, further comprising a strip line formed on said third resin layer.
7. The multi-layer board of claim 5, wherein said third resin layer is provided with an electronic component mounted thereon.
- 25 8. The multi-layer board of claim 5, further comprising a fourth resin layer between said first and third resin layers.

10092548-030802
20080809-0452500T

9. The multi-layer board of claim 5, further comprising:
a polyimide film between said first and third resin layers; and
a capacitor formed on said polyimide film.

5

10. The multi-layer board of claim 1, wherein said first impedance
element is a patterned inductor.

11. The multi-layer board of claim 10, wherein said patterned
inductor is laser-trimmed.

12. The multi-layer board of claim 10, further comprising a ground
pattern formed on said first resin layer excluding a portion corresponding to
said patterned inductor, said ground pattern being formed at an opposite side
to said ceramic layer.

13. The multi-layer board of claim 1, wherein said first impedance
element is a capacitor.

14. The multi-layer board of claim 1, wherein said first impedance
element is a resistor.

15. The multi-layer board of claim 14, wherein said resistor is
laser-trimmed.

16. The multi-layer board of claim 1, further comprising a second
impedance element formed on said ceramic layer at an opposite side to said

1092548-030002

25

first impedance element.

17. The multi-layer board of claim 1, further comprising a strip line formed on said first resin layer.

208020" 84526007